

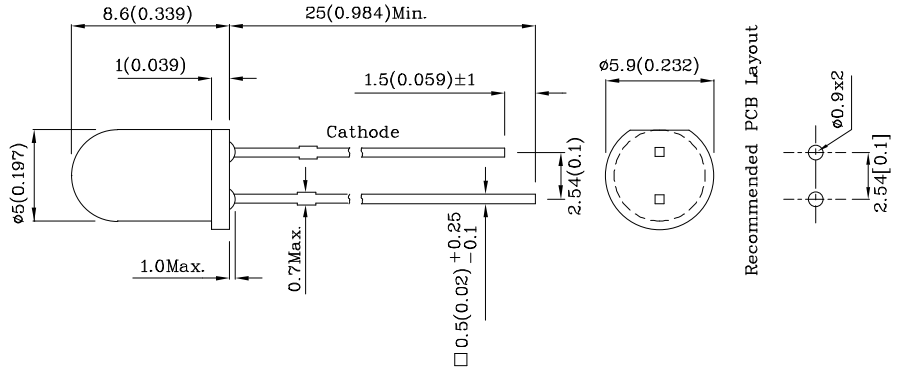
Features

- 5mm package with built-in blinking IC
- Blinking frequency: 3.0Hz to 1.5Hz
- Operation voltage: 3.5V to 14V
- RoHS compliant.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics



- Notes:
1. All dimensions are in millimeters (inches).
 2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
 3. Specifications are subject to change without notice.

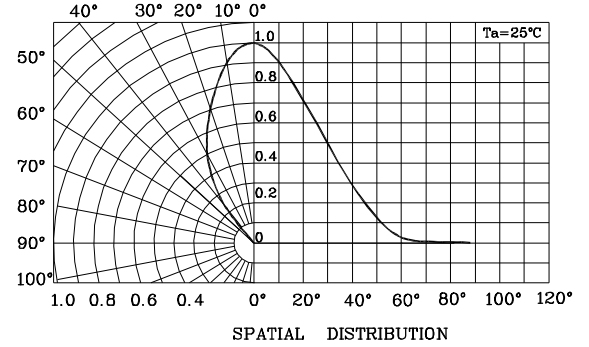
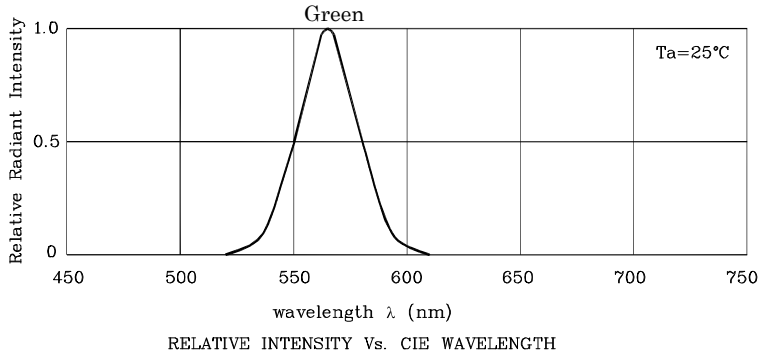
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		Green (GaP)	Unit
Reverse Voltage	V_R	0.5	V
Forward Voltage	V_F	14	V
Power Dissipation	P_D	310	mW
Operating Temperature	T_A	-40 ~ +70	°C
Storage Temperature	T_{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

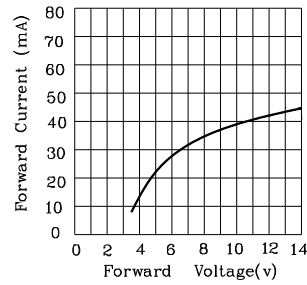
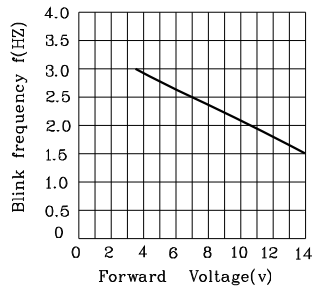
Operating Characteristics ($T_A=25^\circ\text{C}$)		Green (GaP)	Unit
Forward Current (Min.) ($V_F=3.5\text{V}$)	I_F	8	mA
Forward Current (Typ.) ($V_F=5\text{V}$)	I_F	22	mA
Supply Current (Typ.) ($V_F=3.5\text{V}$)	I_{SON}	8	mA
Supply Current (Typ.) ($V_F=14\text{V}$)	I_{SON}	44	mA
Blink Frequency (Min.~Max.) ($V_F=3.5\text{V}\sim 14\text{V}$)	f	1.5~3	Hz
Wavelength of Peak Emission CIE127-2007* (Typ.)	λ_P	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.)	λ_D	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.)	$\Delta\lambda$	30	nm

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* ($V_F=9\text{V}$) mcd		Wavelength CIE127-2007* nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
XBUG53D	Green	GaP	Green Diffused	15*	29*	565*	60°

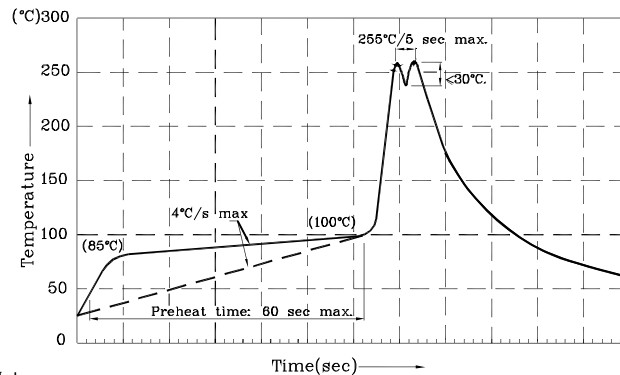
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ Green



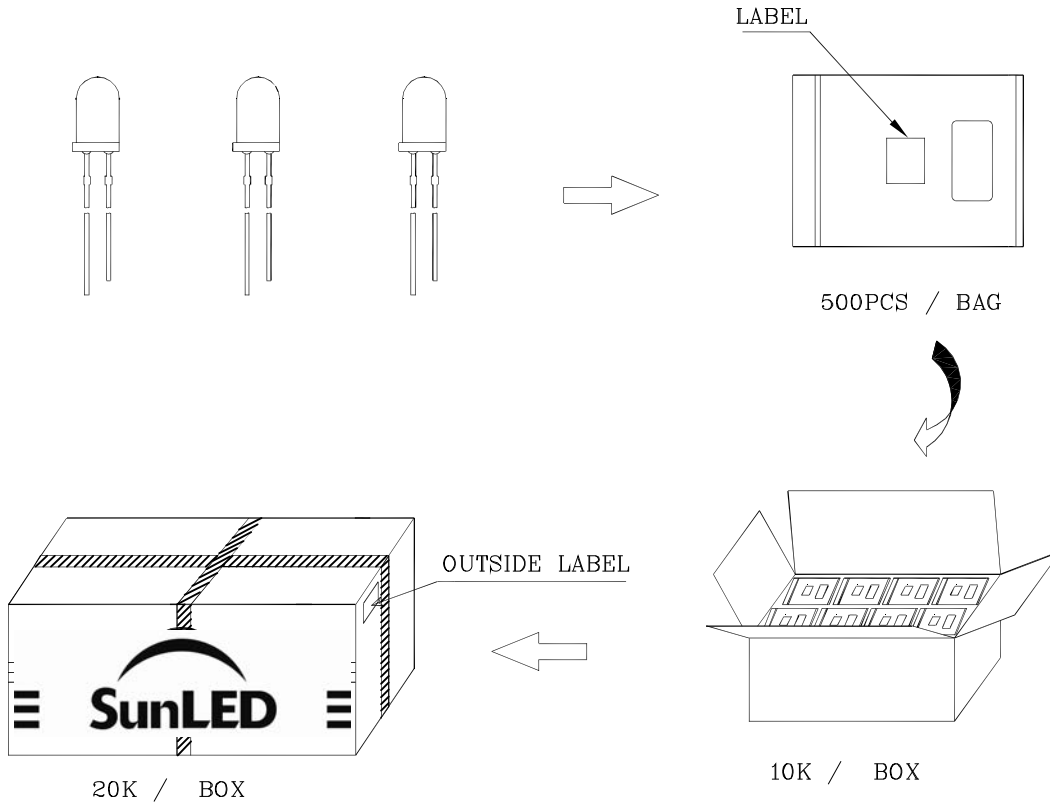
Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)





Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

PACKING & LABEL SPECIFICATIONS



		<table border="1"> <tr><td>Q.C.</td></tr> <tr><td>Q C</td></tr> <tr><td>XX XX. XXXX</td></tr> <tr><td>PASSED</td></tr> </table>	Q.C.	Q C	XX XX. XXXX	PASSED
Q.C.						
Q C						
XX XX. XXXX						
PASSED						
P/NO : XBxxx53x						
QTY : 500 pcs		CODE: XXX				
S/N : XX						
LOT NO:						
 XXXXXXXXXXXXXXXXXXXXXXXX						
RoHS Compliant						

TERMS OF USE

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2. Contents within this document are subject to improvement and enhancement changes without notice.
3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
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6. Additional technical notes are available at <http://www.SunLEDusa.com/TechnicalNotes.asp>